



Material Content Data Sheet



Sales Product Name				BTS50010-1TAD		Issued		31. July 2018	
MA#				MA001630314					
Package				PG-TO263-7-10		Weight*		1558.46 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	12.330	0.79	0.79	7912	7912	
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1186	1186	
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159		
	non noble metal	iron	7439-89-6	0.823	0.05		528		
wire	non noble metal	copper	7440-50-8	822.375	52.77	52.84	527684	528371	
	non noble metal	aluminium	7429-90-5	15.628	1.00	1.00	10028	10028	
encapsulation	organic material	carbon black	1333-86-4	8.270	0.53		5306		
	plastics	epoxy resin	-	90.965	5.84		58369		
	inorganic material	silicondioxide	60676-86-0	452.068	29.01	35.38	290074	353749	
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7804	7804	
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5		
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1887	1892	
solder	non noble metal	tin	7440-31-5	0.157	0.01		101		
	noble metal	silver	7440-22-4	0.196	0.01		126		
	non noble metal	lead	7439-92-1	7.483	0.48	0.50	4801	5028	
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127	
heatspreader	inorganic material	phosphorus	7723-14-0	0.039	0.00		25		
	non noble metal	iron	7439-89-6	0.131	0.01		84		
	non noble metal	copper	7440-50-8	130.589	8.38	8.39	83794	83903	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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